




Thermoplastics hot melt adhesive application for formation of smart card component layer or electronic transponder

Patent number: DE19848712
Publication date: 2000-04-27
Inventor: GRUETZNER JUERGEN (DE); KOLB UWE (DE);
RANFT PAUL (DE); WUESTRICH LIANE (DE)
Applicant: HENKEL KGAA (DE)
Classification:
- **International:** G06K19/077; H05K1/18
- **European:** B29C45/14M2; G06K19/077; G06K19/077M
Application number: DE19981048712 19981022
Priority number(s): DE19981048712 19981022

Also published as:

 WO0025264 (A1)
 EP1123535 (A1)
 CA2347818 (A1)

Abstract of DE19848712

The thermoplastics hot melt adhesive application has a hot melt adhesive material used for providing smart card component layers or electronic transponders, e.g. using low pressure injection molding at a pressure of between 1 and 50 bar and a temperature of between 80 and 250 degrees C. Also included are Independent claims for the following: (a) a smart card manufacturing method; and (b) a multi-layer card body.

Data supplied from the **esp@cenet** database - Worldwide